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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	33MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	50
Program Memory Size	32KB (16K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	902 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC (24.23x24.23)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c756a-33i-l

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NOTES:

7.2.2.2 CPU Status Register (CPUSTA)

The CPUSTA register contains the status and control bits for the CPU. This register has a bit that is used to globally enable/disable interrupts. If only a specific interrupt is desired to be enabled/disabled, please refer to the Interrupt Status (INTSTA) register and the Peripheral Interrupt Enable (PIE) registers. The CPUSTA register also indicates if the stack is available and contains the Power-down (PD) and Time-out (TO) bits. The TO, PD, and STKAV bits are not writable. These bits are set and cleared according to device

logic. Therefore, the result of an instruction with the CPUSTA register as destination may be different than intended.

The $\overrightarrow{\text{POR}}$ bit allows the differentiation between a Power-on Reset, external $\overrightarrow{\text{MCLR}}$ Reset, or a WDT Reset. The BOR bit indicates if a Brown-out Reset occurred.

Note 1: The BOR status bit is a don't care and is not necessarily predictable if the Brown-out circuit is disabled (when the BODEN bit in the Configuration word is programmed).

REGISTER 7-2: CPUSTA REGISTER (ADDRESS: 06h, UNBANKED)

U-0	U-0	R-1	R/W-1	R-1	R-1	R/W-0	R/W-1
_	—	STKAV	GLINTD	TO	PD	POR	BOR
bit 7							bit 0

bit 7-6	Unimplemented: Read as '0'
bit 5	STKAV: Stack Available bit
	This bit indicates that the 4-bit stack pointer value is Fh, or has rolled over from Fh \rightarrow 0h
	(stack overflow).
	 0 = Stack is full, or a stack overflow may have occurred (once this bit has been cleared by a stack overflow, only a device RESET will set this bit)
bit 4	GLINTD: Global Interrupt Disable bit
	This bit disables all interrupts. When enabling interrupts, only the sources with their enable bits set can cause an interrupt.
	1 = Disable all interrupts
1.11.0	
bit 3	TO: WD1 Time-out Status bit
	0 = A Watchdog Timer time-out occurred
bit 2	PD: Power-down Status bit
	1 = After power-up or by the CLRWDT instruction
	0 = By execution of the SLEEP instruction
bit 1	POR: Power-on Reset Status bit
	1 = No Power-on Reset occurred
	0 = A Power-on Reset occurred (must be set by software)
bit 0	BOR: Brown-out Reset Status bit
	When BODEN Configuration bit is set (enabled):
	1 = No Brown-out Reset occurred
	0 = A Brown-out Reset occurred (must be set by software)
	When BODEN Configuration bit is clear (disabled):
	Don't care
	Legend:

Legend:				
R = Readable bit	W = Writable bit	U = Unimplemented	bit, read as '0'	
- n = Value at POR Reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown	

8.2 Table Writes to External Memory

Table writes to external memory are always two-cycle instructions. The second cycle writes the data to the external memory location. The sequence of events for an external memory write are the same for an internal write.

8.2.1 TABLE WRITE CODE

The "i" operand of the TABLWT instruction can specify that the value in the 16-bit TBLPTR register is automatically incremented (for the next write). In Example 8-1, the TBLPTR register is not automatically incremented.

EXAMPLE 8-1: TABLE WRITE

CLRWDT		;	Clear WDT
MOVLW	HIGH (TBL_ADDR)	;	Load the Table
MOVWF	TBLPTRH	;	address
MOVLW	LOW (TBL_ADDR)	;	
MOVWF	TBLPTRL	;	
MOVLW	HIGH (DATA)	;	Load HI byte
TLWT	1, WREG	;	in TABLATH
MOVLW	LOW (DATA)	;	Load LO byte
TABLWT	0,0,WREG	;	in TABLATL
		;	and write to
		;	program memory
		;	(Ext. SRAM)

FIGURE 8-5: TABLWT WRITE TIMING (EXTERNAL MEMORY)



10.4 PORTD and DDRD Registers

PORTD is an 8-bit bi-directional port. The corresponding data direction register is DDRD. A '1' in DDRD configures the corresponding port pin as an input. A '0' in the DDRD register configures the corresponding port pin as an output. Reading PORTD reads the status of the pins, whereas writing to PORTD will write to the port latch. PORTD is multiplexed with the system bus. When operating as the system bus, PORTD is the high order byte of the address/data bus (AD15:AD8). The timing for the system bus is shown in the Electrical Specifications section.

Note: This port is configured as the system bus when the device's configuration bits are selected to Microprocessor or Extended Microcontroller modes. In the two other microcontroller modes, this port is a general purpose I/O. Example 10-4 shows an instruction sequence to initialize PORTD. The Bank Select Register (BSR) must be selected to Bank 1 for the port to be initialized. The following example uses the MOVLB instruction to load the BSR register for bank selection.

EXAMPLE 10-4: INITIALIZING PORTD

MOVLB	1	;	Select Bank 1
CLRF	PORTD,	F;	Initialize PORTD data
		;	latches before setting
		;	the data direction reg
MOVLW	0xCF	;	Value used to initialize
		;	data direction
MOVWF	DDRD	;	Set RD<3:0> as inputs
		;	RD<5:4> as outputs
		;	RD<7:6> as inputs

FIGURE 10-10: BLOCK DIAGRAM OF RD7:RD0 PORT PINS (IN I/O PORT MODE)



10.9 PORTJ and DDRJ Registers (PIC17C76X only)

PORTJ is an 8-bit wide, bi-directional port. The corresponding data direction register is DDRJ. A '1' in DDRJ configures the corresponding port pin as an input. A '0' in the DDRJ register configures the corresponding port pin as an output. Reading PORTJ reads the status of the pins, whereas writing to PORTJ will write to the respective port latch.

PORTJ is a general purpose I/O port.

EXAMPLE 10-9: INITIALIZING PORTJ

MOVLB	8	;	Select Bank 8
CLRF	PORTJ,	F;	Initialize PORTJ data
		;	latches before setting
		;	the data direction
		;	register
MOVLW	0xCF	;	Value used to initialize
		;	data direction
MOVWF	DDRJ	;	Set RJ<3:0> as inputs
		;	RJ<5:4> as outputs
		;	RJ<7:6> as inputs





13.1.3.1 PWM Periods

The period of the PWM1 output is determined by Timer1 and its period register (PR1). The period of the PWM2 and PWM3 outputs can be individually software configured to use either Timer1 or Timer2 as the timebase. For PWM2, when TM2PW2 bit (PW2DCL<5>) is clear, the time base is determined by TMR1 and PR1 and when TM2PW2 is set, the time base is determined by Timer2 and PR2. For PWM3, when TM2PW3 bit (PW3DCL<5>) is clear, the time base is determined by TMR1 and PR1, and when TM2PW3 is set, the time base is determined by Timer2 and PR2.

Running two different PWM outputs on two different timers allows different PWM periods. Running all PWMs from Timer1 allows the best use of resources by freeing Timer2 to operate as an 8-bit timer. Timer1 and Timer2 cannot be used as a 16-bit timer if any PWM is being used.

The PWM periods can be calculated as follows:

period of PWM1 = $[(PR1) + 1] \times 4TOSC$

period of PWM2 = $[(PR1) + 1] \times 4TOSC$ or $[(PR2) + 1] \times 4TOSC$

period of PWM3 =
$$[(PR1) + 1] \times 4TOSC$$
 or
 $[(PR2) + 1] \times 4TOSC$

The duty cycle of PWMx is determined by the 10-bit value DCx<9:0>. The upper 8-bits are from register PWxDCH and the lower 2-bits are from PWxDCL<7:6> (PWxDCH:PWxDCL<7:6>). Table 13-4 shows the maximum PWM frequency (FPWM), given the value in the period register.

The number of bits of resolution that the PWM can achieve depends on the operation frequency of the device as well as the PWM frequency (FPWM).

Maximum PWM resolution (bits) for a given PWM frequency:

$$= \frac{\log\left(\frac{FOSC}{FPWM}\right)}{\log\left(2\right)} \quad \text{bits}$$

where: FPWM = 1 / period of PWM

The PWMx duty cycle is as follows:

PWMx Duty Cycle = $(DCx) \times TOSC$

where DCx represents the 10-bit value from PWxDCH:PWxDCL.

If DCx = 0, then the duty cycle is zero. If PRx = PWxDCH, then the PWM output will be low for one to four Q-clocks (depending on the state of the PWxDCL<7:6> bits). For a duty cycle to be 100%, the PWxDCH value must be greater then the PRx value.

The duty cycle registers for both PWM outputs are double buffered. When the user writes to these registers, they are stored in master latches. When TMR1 (or TMR2) overflows and a new PWM period begins, the master latch values are transferred to the slave latches and the PWMx pin is forced high.

Note:	For PW1DCH, PW1DCL, PW2DCH,
	PW2DCL, PW3DCH and PW3DCL regis-
	ters, a write operation writes to the "master
	latches", while a read operation reads the
	"slave latches". As a result, the user may
	not read back what was just written to the
	duty cycle registers (until transferred to
	slave latch).

The user should also avoid any "read-modify-write" operations on the duty cycle registers, such as: ADDWF PW1DCH. This may cause duty cycle outputs that are unpredictable.

TABLE 13-4:	PWM FREQUENCY vs.
	RESOLUTION AT 33 MHz

PWM	Frequency (kHz)						
Frequency	32.2	64.5	90.66	128.9	515.6		
PRx Value	0xFF	0x7F	0x5A	0x3F	0x0F		
High Resolution	10-bit	9-bit	8.5-bit	8-bit	6-bit		
Standard Resolution	8-bit	7-bit	6.5-bit	6-bit	4-bit		

13.1.3.2 PWM INTERRUPTS

The PWM modules make use of the TMR1 and/or TMR2 interrupts. A timer interrupt is generated when TMR1 or TMR2 equals its period register and on the following increment is cleared to zero. This interrupt also marks the beginning of a PWM cycle. The user can write new duty cycle values before the timer rollover. The TMR1 interrupt is latched into the TMR1IF bit and the TMR2 interrupt is latched into the TMR2IF bit. These flags must be cleared in software.

FIGURE 14-1: USART TRANSMIT









FIGURE 15-9: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)



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15.2.1.3 Slave Transmission

When the R/\overline{W} bit of the incoming address byte is set and an address match occurs, the R/\overline{W} bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The \overline{ACK} pulse will be sent on the ninth bit, and the SCL pin is held low. The transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then SCL pin should be enabled by setting bit CKP (SSPCON1<4>). The master must monitor the SCL pin prior to asserting another clock pulse. The slave devices may be holding off the master by stretching the clock. The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 15-13). An SSP interrupt is generated for each data transfer byte. The SSPIF flag bit must be cleared in software, and the SSPSTAT register is used to determine the status of the byte transfer. The SSPIF flag bit is set on the falling edge of the ninth clock pulse.

As a slave-transmitter, the ACK pulse from the masterreceiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line was high (not ACK), then the data transfer is complete. When the not ACK is latched by the slave, the slave logic is reset and the slave then monitors for another occurrence of the START bit. If the SDA line was low (ACK), the transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then, the SCL pin should be enabled by setting the CKP bit.

FIGURE 15-12: I²C WAVEFORMS FOR RECEPTION (7-BIT ADDRESS)



FIGURE 15-13: I²C WAVEFORMS FOR TRANSMISSION (7-BIT ADDRESS)



15.2.9 I²C MASTER MODE START CONDITION TIMING

To initiate a START condition, the user sets the START condition enable bit, SEN (SSPCON2<0>). If the SDA and SCL pins are sampled high, the baud rate generator is reloaded with the contents of SSPADD<6:0> and starts its count. If SCL and SDA are both sampled high when the baud rate generator times out (TBRG), the SDA pin is driven low. The action of the SDA being driven low while SCL is high is the START condition and causes the S bit (SSPSTAT<3>) to be set. Following this, the baud rate generator is reloaded with the contents of SSPADD<6:0> and resumes its count. When the baud rate generator times out (TBRG), the SEN bit (SSPCON2<0>) will be automatically cleared by hardware, the baud rate generator is suspended, leaving the SDA line held low and the START condition is complete.

Note: If at the beginning of START condition, the SDA and SCL pins are already sampled low, or if during the START condition, the SCL line is sampled low before the SDA line is driven low, a bus collision occurs. The Bus Collision Interrupt Flag (BCLIF) is set, the START condition is aborted and the I²C module is reset into its IDLE state.

FIGURE 15-20: FIRST START BIT TIMING



If the user writes the SSPBUF when a START sequence is in progress, then WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

Note: Because queueing of events is not allowed, writing to the lower 5 bits of SSPCON2 is disabled until the START condition is complete.



15.2.12 I²C MASTER MODE RECEPTION

Master mode reception is enabled by programming the receive enable bit, RCEN (SSPCON2<3>).

Note:	The SSP Module must be in an IDLE
	STATE before the RCEN bit is set, or the
	RCEN bit will be disregarded.

The baud rate generator begins counting and on each rollover, the state of the SCL pin changes (high to low/ low to high) and data is shifted into the SSPSR. After the falling edge of the eighth clock, the receive enable flag is automatically cleared, the contents of the SSPSR are loaded into the SSPBUF, the BF flag is set, the SSPIF is set and the baud rate generator is suspended from counting, holding SCL low. The SSP is now in IDLE state, awaiting the next command. When the buffer is read by the CPU, the BF flag is automatically cleared. The user can then send an acknowledge bit at the end of reception, by setting the acknowledge sequence enable bit, ACKEN (SSPCON2<4>).

15.2.12.1 BF Status Flag

In receive operation, BF is set when an address or data byte is loaded into SSPBUF from SSPSR. It is cleared when SSPBUF is read.

15.2.12.2 SSPOV Status Flag

In receive operation, SSPOV is set when 8 bits are received into the SSPSR, and the BF flag is already set from a previous reception.

15.2.12.3 WCOL Status Flag

If the user writes the SSPBUF when a receive is already in progress (i.e., SSPSR is still shifting in a data byte), then WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

EXAMPLE 15-2: INTERFACING TO A 24LC01B SERIAL EEPROM (USING MPLAB C17)

```
void ACKPoll(void)
{
                                             // Send start bit
         StartI2C();
        IdleI2C();
                                            // Wait for idle condition
        WriteI2C(CONTROL);
                                            // Send control byte
        IdleI2C();
                                            // Wait for idle condition
         // Poll the ACK bit coming from the 24LC01B
         // Loop as long as the 24LC01B NACKs \,
        while (SSPCON2bits.ACKSTAT)
         {
                                         // Send a restart bit
                 RestartI2C();
                 IdleI2C(); // Wait for idle condition
WriteI2C(CONTROL); // Send control byte
IdleI2C(); // Wait for idle condition
         }
         IdleI2C();
                                            // Wait for idle condition
                                            // Send stop bit
         StopI2C();
         IdleI2C();
                                            // Wait for idle condition
         return;
}
```

17.4 Power-down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction. This clears the Watchdog Timer and postscaler (if enabled). The PD bit is cleared and the TO bit is set (in the CPUSTA register). In SLEEP mode, the oscillator driver is turned off. The I/O ports maintain their status (driving high, low, or hi-impedance input).

The MCLR/VPP pin must be at a logic high level (VIHMC). A WDT time-out RESET does not drive the MCLR/VPP pin low.

17.4.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

- Power-on Reset
- · Brown-out Reset
- External RESET input on MCLR/VPP pin
- WDT Reset (if WDT was enabled)
- Interrupt from RA0/INT pin, RB port change, T0CKI interrupt, or some peripheral interrupts

The following peripheral interrupts can wake the device from SLEEP:

- Capture interrupts
- · USART synchronous slave transmit interrupts
- · USART synchronous slave receive interrupts
- A/D conversion complete
- · SPI slave transmit/receive complete
- I²C slave receive

Other peripherals cannot generate interrupts since during SLEEP, no on-chip Q clocks are present.

Any RESET event will cause a device RESET. Any interrupt event is considered a continuation of program execution. The TO and PD bits in the CPUSTA register can be used to determine the cause of a device RESET. The PD bit, which is set on power-up, is cleared when SLEEP is invoked. The TO bit is cleared if WDT time-out occurred (and caused a RESET).

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GLINTD bit. If the GLINTD bit is set (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GLINTD bit is clear (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt vector address. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

Note:	If the global interrupt is disabled (GLINTD
	is set), but any interrupt source has both its
	interrupt enable bit and the corresponding
	interrupt flag bit set, the device will imme-
	diately wake-up from SLEEP. The \overline{TO} bit is
	set and the \overline{PD} bit is cleared.

The WDT is cleared when the device wakes from SLEEP, regardless of the source of wake-up.

17.4.1.1 Wake-up Delay

When the oscillator type is configured in XT or LF mode, the Oscillator Start-up Timer (OST) is activated on wake-up. The OST will keep the device in RESET for 1024Tosc. This needs to be taken into account when considering the interrupt response time when coming out of SLEEP.

0004h

Inst (PC+2)

Inst (PC+1)

Q4

0005h

Dummy Cycle

FIGURE 17-2: WAKE-UP FROM SLEEP THROUGH INTERRUPT Q1 | Q2 | Q3 | Q4 | Q1 Q2 Q3 OSC1 MMM Tost(2) CLKOUT⁽⁴⁾ '0' or '1 INT (RA0/INT pin) Interrupt Latency(2) **INTF Flag** GLINTD bit Processor in SLEEP INSTRUCTION FLOW

Note 1: XT or LF oscillator mode assumed.

Inst (PC) = SLEEP

Inst (PC-1)

2: TOST = 1024TOSC (drawing not to scale). This delay will not be there for RC osc mode.

PC+1

Inst (PC+1)

SLEEP

3: When GLINTD = 0, processor jumps to interrupt routine after wake-up. If GLINTD = 1, execution will continue in line. 4: CLKOUT is not available in these osc modes, but shown here for timing reference.

PC+2

PC

Instruction

Fetched Instruction

Executed

RET	URN	Return fr	om Sub	routine		
Synt	ax:	[label]	RETUR	N		
Ope	rands:	None				
Ope	ration:	$TOS \rightarrow PC;$				
Statu	us Affected:	None				
Enco	oding:	0000	0000	0000	0010	
Des	cription:	Return fror popped an is loaded in	n subrout d the top nto the pr	ine. The s of the sta ogram co	stack is ck (TOS) unter.	
Wor	ds:	1				
Cycl	es:	2				
QC	vcle Activity:					
	Q1	Q2	Q3	3	Q4	
	Decode	No operation	Proce Dat	ess F a fro	POP PC	
	No operation	No operation	No opera	tion o	No peration	
			•			

Example: RETURN

After Interrupt PC = TOS

RLCF	Rotate L	eft f thro	ugh Car	ry
Syntax:	[label]	RLCF 1	f,d	
Operands:	0 ≤ f ≤ 25 d ∈ [0,1]	5		
Operation:	$f < n > \rightarrow d$ $f < 7 > \rightarrow C$ $C \rightarrow d < 0$	<n+1>; ;; ></n+1>		
Status Affected:	С			
Encoding:	0001	101d	ffff	ffff
Words:	WREG. If back in rec	d' is 1, the gister 'f'.	ster f	stored
Q Cycle Activity:	I			
Q1	Q2	Q3		Q4
Decode	Read register 'f'	Proces Data	s W des	rite to tination
Example: Before Instru	RLCF	REG,0	1	
REG	= 1110 0	110		

After Instruction

ter Instruc	tion		
REG	=	1110	0110
WREG	=	1100	1100
С	=	1	

TLW	Т	Та	ble Lat	ch Writ	е		
Synt	ax:	[<i>la</i>	abel]	LWT t,f			
Ope	rands:	0 ⊴ t ∈	≤ f ≤ 258 ⊧ [0,1]	5			
Ope	ration:	lft f– lft f–	: = 0, → TBLA : = 1, → TBLA	TL; TH			
Statu	us Affected:	No	one				
Enco	oding:		1010	01tx	fff	f	ffff
Des	cription:	Da the If t If t Th wit me	ta from f = 16-bit ta = 1; high = 0; low is instruc h TABLW emory to	ile registe able latch n byte is byte is v ction is us rT to tran program	er 'f' is n (TBL writter vritten sed in sfer d memo	conj ata f	ten into junction rom data
Wor	ds:	1					
Cycl	es:	1					
QC	ycle Activity:						
	Q1		Q2	Q3	3		Q4
	Decode	F reg	Read ister 'f'	Proce Dat	ess a	r TB T	Write egister LATH or BLATL
Exar	mple:	TL	WT	t, RAM			
	Before Instru	ictior	n				
	t	=	0				
	RAM TBLAT	=	0xB7 0x0000	(TBLA (TBLA	TH = (TL = (0x00)x00)))
	After Instruct	ion					
	RAM TBLAT	=	0xB7 0x00B7	(TBLA (TBLA	(TH = TL = (0x0()xB7))

Before Instruction

	t	=	1	
	RAM	=	0xB7	
	TBLAT	=	0x0000	(TBLATH = 0x00)
				(TBLATL = 0x00)
Afte	r Instruct	ion		
	RAM	=	0xB7	
	TBLAT	=	0xB700	(TBLATH = 0xB7) (TBLATL = 0x00)

TST	FSZ	Test f, ski	p if 0			
Synt	ax:	[label] T	STFSZ f			
Ope	rands:	$0 \le f \le 255$	5			
Ope	ration:	skip if f = 0	D			
Statu	us Affected:	None				
Enco	oding:	0011	0011 fff	f ffff		
Desc	cription:	If 'f' = 0, the next instruction, fetched during the current instruction execut is discarded and a NOP is executed making this a two-cycle instruction.				
Word	ds:	1				
Cycl	es:	1 (2)				
QC	cle Activity:					
	Q1	Q2	Q3	Q4		
	Decode	Read register 'f'	Process Data	No operation		
lf ski	p:					
	Q1	Q2	Q3	Q4		
	No operation	No operation	No operation	No operation		
<u>Exar</u>	nple:	HERE T NZERO ZERO	ISTFSZ CNT : :			
	Before Instru PC = Ado	iction dress (HERE)				
	After Instruct If CNT PC If CNT PC	ion = 0x = Ad ¼ 0x = Ad	00, dress (ZERO) 00, dress (NZERO))		

20.0 PIC17C7XX ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias	55°C to +125°C
Storage temperature	65°C to +150°C
Voltage on VDD with respect to Vss	0 V to +7.5 V
Voltage on MCLR with respect to Vss (Note 2)	0.3 V to +14 V
Voltage on RA2 and RA3 with respect to Vss	0.3 V to +8.5 V
Voltage on all other pins with respect to Vss	0.3 V to VDD + 0.3 V
Total power dissipation (Note 1)	1.0 W
Maximum current out of Vss pin(s) - total (@ 70°C)	500 mA
Maximum current into VDD pin(s) - total(@ 70°C)	500 mA
Input clamp current, Iк (Vi < 0 or Vi > VDD)	±20 mA
Output clamp current, Iок (Vo < 0 or Vo > Voo)	±20 mA
Maximum output current sunk by any I/O pin (except RA2 and RA3)	35 mA
Maximum output current sunk by RA2 or RA3 pins	60 mA
Maximum output current sourced by any I/O pin	20 mA
Maximum current sunk by PORTA and PORTB (combined)	150 mA
Maximum current sourced by PORTA and PORTB (combined)	100 mA
Maximum current sunk by PORTC, PORTD and PORTE (combined)	150 mA
Maximum current sourced by PORTC, PORTD and PORTE (combined)	100 mA
Maximum current sunk by PORTF and PORTG (combined)	150 mA
Maximum current sourced by PORTF and PORTG (combined)	100 mA
Maximum current sunk by PORTH and PORTJ (combined)	150 mA
Maximum current sourced by PORTH and PORTJ (combined)	100 mA
Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - \sum IOH} + \sum {(VD	D-VOH) x IOH} + Σ (VOL x IOL)

2: Voltage spikes below Vss at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100 Ω should be used when applying a "low" level to the $\overline{\text{MCLR}}$ pin, rather than pulling this pin directly to Vss.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.



FIGURE 20-13: SPI MASTER MODE TIMING (CKE = 0)

TABLE 20-8: SPI MODE REQUIREMENTS (MASTER MODE, CKE = 0)

Param. No.	Symbol	Characteristic		Min	Тур†	Max	Units	Conditions
70	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK \downarrow or SCK \uparrow input		Тсу	—		ns	
71	TscH	SCK input high time	Continuous	1.25Tcy + 30	—	Ι	ns	
71A		(Slave mode)	Single Byte	40	—	Ι	ns	(Note 1)
72	TscL	SCK input low time	Continuous	1.25Tcy + 30	—	Ι	ns	
72A		(Slave mode)	Single Byte	40	—	Ι	ns	(Note 1)
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to	Setup time of SDI data input to SCK edge		—		ns	
73A	Тв2в	Last clock edge of Byte1 to the of Byte2	Last clock edge of Byte1 to the 1st clock edge of Byte2		—	_	ns	(Note 1)
74	TscH2diL, TscL2diL	Hold time of SDI data input to S	SCK edge	100	—	_	ns	
75	TdoR	SDO data output rise time		—	10	25	ns	
76	TdoF	SDO data output fall time		—	10	25	ns	
78	TscR	SCK output rise time (Master m	node)	—	10	25	ns	
79	TscF	SCK output fall time (Master m	ode)	—	10	25	ns	
80	TscH2doV, TscL2doV	SDO data output valid after SC	K edge	—	—	50	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

Note 1: Specification 73A is only required if specifications 71A and 72A are used.



TABLE 20-13: I²C BUS DATA REQUIREMENTS

Param No.	Sym	Character	istic	Min	Max	Units	Conditions
100	Thigh	Clock high time	100 kHz mode	2(Tosc)(BRG + 1)	—	ms	
			400 kHz mode	2(Tosc)(BRG + 1)	—	ms	
			1 MHz mode ⁽¹⁾	2(Tosc)(BRG + 1)	_	ms	
101	Tlow	Clock low time	100 kHz mode	2(Tosc)(BRG + 1)	_	ms	
			400 kHz mode	2(Tosc)(BRG + 1)	_	ms	
			1 MHz mode ⁽¹⁾	2(Tosc)(BRG + 1)	_	ms	
102	Tr	SDA and SCL rise time	100 kHz mode		1000	ns	Cb is specified to be from
			400 kHz mode	20 + 0.1Cb	300	ns	10 to 400 pF
			1 MHz mode ⁽¹⁾		300	ns	
103	Tf	SDA and SCL fall time	100 kHz mode		300	ns	Cb is specified to be from
			400 kHz mode	20 + 0.1Cb	300	ns	10 to 400 pF
			1 MHz mode ⁽¹⁾		10	ns	
90	Tsu:sta	START condition setup	100 kHz mode	2(Tosc)(BRG + 1)	—	ms	Only relevant for Repeated
		time	400 kHz mode	2(Tosc)(BRG + 1)	—	ms	Start condition
			1 MHz mode ⁽¹⁾	2(Tosc)(BRG + 1)	—	ms	
91	Thd:sta	START condition hold	100 kHz mode	2(Tosc)(BRG + 1)	—	ms	After this period, the first
		time	400 kHz mode	2(Tosc)(BRG + 1)	_	ms	clock pulse is generated
			1 MHz mode ⁽¹⁾	2(Tosc)(BRG + 1)	_	ms	
106	Thd:dat	Data input hold time	100 kHz mode	0	_	ns	
			400 kHz mode	0	0.9	ms	
			1 MHz mode ⁽¹⁾	0	_	ns	
107	Tsu:dat	Data input setup time	100 kHz mode	250	_	ns	(Note 2)
			400 kHz mode	100	_	ns	
			1 MHz mode ⁽¹⁾	100	_	ns	
92	Tsu:sto	STOP condition	100 kHz mode	2(Tosc)(BRG + 1)		ms	
		setup time	400 kHz mode	2(Tosc)(BRG + 1)		ms	
			1 MHz mode ⁽¹⁾	2(Tosc)(BRG + 1)	-	ms	
109	Таа	Output valid from clock	100 kHz mode		3500	ns	
			400 kHz mode		1000	ns	
			1 MHz mode ⁽¹⁾		400	ns	

Note 1: Maximum pin capacitance = 10 pF for all I^2C pins.

2: A fast mode (400 KHz) I²C bus device can be used in a standard mode I²C bus system, but the parameter # 107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line. Parameter #102 + #107 = 1000 + 250 = 1250 ns (for 100 kHz mode) before the SCL line is released.

3: C_b is specified to be from 10-400pF. The minimum specifications are characterized with $C_b=10pF$. The rise time spec (t_r) is characterized with $R_p=R_p$ min. The minimum fall time specification (t_f) is characterized with $C_b=10pF$, and $R_p=R_p$ max. These are only valid for fast mode operation (VDD=4.5-5.5V) and where the SPM bit (SSPSTAT<7>) =1.)

4: Max specifications for these parameters are valid for falling edge only. Specs are characterized with R_p=R_p min and C_b=400pF for standard mode, 200pF for fast mode, and 10pF for 1MHz mode.

FIGURE 20-21: USART ASYNCHRONOUS MODE START BIT DETECT



TABLE 20-16: USART ASYNCHRONOUS MODE START BIT DETECT REQUIREMENTS

Param No.	Sym	Characteristic		Min	Тур	Max	Unit s	Conditions
120A	TdtL2ckH	Time to ensure that the RX pin is sar	mpled low		_	TCY	ns	
121A	TdtRF	Data rise time and fall time	Receive	_	_	(Note 1)	ns	
			Transmit	_	_	40	ns	
123A	TckH2bckL	Time from RX pin sampled low to firs of x16 clock	t rising edge			Тсү	ns	

Note 1: Schmitt trigger will determine logic level.

FIGURE 20-22: USART ASYNCHRONOUS RECEIVE SAMPLING WAVEFORM



TABLE 20-17: USART ASYNCHRONOUS RECEIVE SAMPLING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур	Max	Unit s	Conditions
125A	TdtL2ckH	Setup time of RX pin to first data sampled	TCY	—	_	ns	
126A	TdtL2ckH	Hold time of RX pin from last data sam- pled	Тсү		_	ns	

CALL	200
0/(EE	207
CLRF	207
CLRWDT	
COMF	
CPFSEQ	
CPFSGI	
DAW	
	212
	213 214
INCESZ	213
IOBI W	214
IORWE	215
LCALL	
MOVFP	
MOVLB	
MOVLR	217
MOVLW	217
MOVPF	218
MOVWF	218
MULLW	219
MULWF	219
NEGW	220
NOP	220
RETFIE	221
RETLW	
RETURN	
RLCF	
RLNCF	
	224
SETFSETF	224 225
OLLLI	
SUBI W	
SUBLW SUBWF	
SUBLW SUBWF SUBWFB	
SUBLW SUBWF SUBWFB SWAPF	
SUBLW SUBWF SUBWFB SWAPF TABLRD	
SUBLW SUBWF SUBWFB SWAPF TABLRD TABLRT	
SUBLW SUBWF SUBWFB SWAPF TABLRD TABLWT TLRD.	
SUBLW SUBWF SUBWFB SWAPF TABLRD TABLWT TLRD TLRD	
SUBLW SUBWF SUBWFB SWAPF TABLRD TABLWT TLRD TLRD TLWT TSTFSZ	225 226 226 227 227, 228 227, 228 229 229 230 230
SUBLW SUBWF SUBWFB SWAPF TABLRD TABLWT TLRD TLRD TLWT TSTFSZ XORLW	225 226 226 227 227, 228 229 229 229 230 230 231
SUBLWSUBWFSUBWFSUBWFBSUBWFBSWAPFTABLRDTABLRTTABLWTTLRDTLRTTLRTTSTFSZSORLWSORWF.	225 226 226 227 227, 228 229 229 230 230 230 231 231
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SUBLW SUBWF SUBWFB SWAPF TABLRD TABLWT TLRD TLWT TSTFSZ XORWF Instruction Set Summary Instructions TABLRD TLRD INTPR	225 226 226 227 227, 228 229 229 230 230 231 231 197
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SUBLW SUBWF SUBWFB SWAPF TABLRD TABLWT TLRD TLWT TSTFSZ XORWF Instruction Set Summary Instructions TABLRD TLRD INT Pin INTEDG Inter-Integrated Circuit (I ² C)	225 226 227 227, 228 229 229 230 230 231 231 197 64 64 64 40 34 53, 97 133
SUBLW SUBWF SUBWFB SWAPF TABLRD TABLWT TLRD TLWT TSTFSZ XORWF Instruction Set Summary Instructions TABLRD TLRD INT Pin INTEDG Inter-Integrated Circuit (I ² C) Interal Sampling Switch (Bss) Impedence	225 226 226 227 227, 228 229 230 230 230 231 231 197 64 64 64 40 34 53, 97 133 183
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SUBLWSUBWFSUBWFBSUBWFBSWAPFTABLRDTABLRDTABLWTTLRDTLRDTLWTTSTFSZSORLWSORWFInstruction Set SummaryInstructions TABLRDTLRDINTPININTEINTEDGInter-Integrated Circuit (I ² C)Internal Sampling Switch (Rss) ImpedenceInterrupt on Change FeatureInterrupt Status Register (INTSTA)	225 226 227 227, 228 229 229 230 230 230 231 231 197 64 64 64 40 34 53, 97 133 183 74 34
SUBLW SUBWF SUBWFB SWAPF TABLRD TABLWT TLRD TLWT TSTFSZ XORWF Instruction Set Summary Instructions TABLRD TLRD INT Pin INTE INTEDG Inter-Integrated Circuit (I ² C) Interrupt Status Register (INTSTA) Interrupts	225 226 227 227, 228 229 230 230 230 231 231 197
SUBLW SUBWF SUBWFB SWAPF TABLRD TABLWT TLRD TLWT TSTFSZ XORWF Instruction Set Summary Instructions TABLRD TLRD INT Pin INTE INTEDG Inter-Integrated Circuit (I ² C) Interrupt on Change Feature Interrupt Status Register (INTSTA) Interrupts A/D Interrupt	225 226 226 227, 228 229 229 230 230 230 231 231 231 197 64 4
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SUBLW SUBWF SUBWFB SWAPF TABLRD TABLRD TLRD TLRD TLRD TLRV TSTFSZ XORLW XORWF Instruction Set Summary Instructions TABLRD TABLRD INTFIN INTE INTE INTEDG Inter-Integrated Circuit (I ² C) Internal Sampling Switch (Rss) Impedence Interrupt on Change Feature Interrupt Status Register (INTSTA) Interrupts A/D Interrupt Bus Collision Interrupt Capture2 Interrupt	225 226 226 227, 228 229 229 230 230 230 231 231 197 64 4
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TMB2IE 33
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PIP1 Degister 27
PIRT Register
PIR2 Register
PORTB Interrupt on Change
PWM108
RA0/INT
Status Register
Synchronous Serial Port Interrupt
TOCKI Interrupt 30
Timing 40
TMD1 Overfleve Interrupt
TMRT Overnow Interrupt
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